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(57) **ABSTRACT**

A wiring board includes an insulating layer, a thin film capacitor laminated on the insulating layer, an interconnect layer electrically connected to the thin film capacitor, and an encapsulating resin layer laminated on the thin film capacitor. The interconnect layer includes a pad protruding from the thin film capacitor. The encapsulating resin layer is a mold resin having a non-photosensitive thermosetting resin as a main component thereof. The encapsulating resin layer exposes a top surface of the pad, and covers at least a portion of a side surface of the pad.

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